#### **DISCRETE SEMICONDUCTORS**

## DATA SHEET

# BYC8B-600 Rectifier diode ultrafast, low switching loss

**Product specification** 

March 2001



**NXP Semiconductors Product specification** 

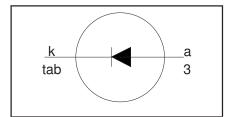
#### Rectifier diode ultrafast, low switching loss

**BYC8B-600** 

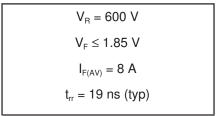
#### **FEATURES**

- · Extremely fast switching
- Low reverse recovery current
- · Low thermal resistance
- · Reduces switching losses in associated MOSFET

#### **SYMBOL**



#### **QUICK REFERENCE DATA**



#### **APPLICATIONS**

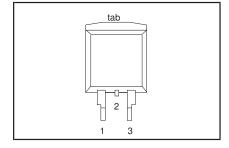
- Active power factor correction
- Half-bridge lighting ballastsHalf-bridge/ full-bridge switched mode power supplies.

The BYC8B-600 is supplied in the SOT404 surface mounting package.

#### **PINNING**

PIN	PIN DESCRIPTION		
1 no connection			
2	cathode <sup>1</sup>		
3	anode		
tab	cathode		

#### **SOT404**



#### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	Peak repetitive reverse voltage		-	600	V
V <sub>RWM</sub>	Crest working reverse voltage		-	600	l v
V <sub>R</sub>	Continuous reverse voltage	T <sub>mb</sub> ≤ 110 °C	-	500	l v
I <sub>F(AV)</sub>	Average forward current	$\delta = 0.5$ ; with reapplied $V_{RRM(max)}$ ;	-	8	Α
I <sub>FRM</sub>	Repetitive peak forward current	$T_{mb} \le 82  ^{\circ}C$ $\delta = 0.5$ ; with reapplied $V_{RRM(max)}$ ; $T_{mb} \le 82  ^{\circ}C$	-	16	A
I <sub>FSM</sub>	Non-repetitive peak forward current.	t = 10 ms t = 8.3 ms	- -	55 60	A A
		sinusoidal; $T_j = 150^{\circ}C$ prior to surge with reapplied $V_{RWM(max)}$			
T <sub>stg</sub>	Storage temperature	, ,	-40	150	, C
T <sub>i</sub> *	Operating junction temperature		-	150	°C

#### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-mb</sub>	Thermal resistance junction to mounting base		-	-	2.2	K/W
R <sub>th j-a</sub>		minimum footprint, FR4 board	-	50	-	K/W

<sup>1</sup> it is not possible to make connection to pin 2 of the SOT404 package

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#### **ELECTRICAL CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	Forward voltage	$I_F = 8 \text{ A}; T_{\perp} = 150^{\circ}\text{C}$	-	1.4	1.85	V
		$I_F = 16 \text{ Å}; T_j = 150^{\circ}\text{C}$	-	1.7	2.3	V
I <sub>R</sub>	Reverse current	$I_F = 8 \text{ A};$ $V_R = 600 \text{ V}$	-	2.0	2.9 150	μĄ
		$V_{R} = 500 \text{ V}; T_{j} = 100 \text{ °C}$	-	1.1	3.0	mA
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A/}\mu\text{s}$	-	30	52	ns
t <sub>rr</sub>	Reverse recovery time	$I_{F} = 8 \text{ A}; V_{R} = 400 \text{ V};$ $dI_{F}/dt = 500 \text{ A/}\mu\text{s}$	-	19	-	ns
t <sub>rr</sub>	Reverse recovery time	$I_F = 8 \text{ A}; V_R = 400 \text{ V};$ $I_F = 8 \text{ A}; V_R = 400 \text{ V};$ $I_F = 100 \text{ C}$	-	32	40	ns
I <sub>rrm</sub>	Peak reverse recovery current	$I_F = 8 \text{ A}; V_R = 400 \text{ V};$ $dI_F/dt = 50 \text{ A/}\mu\text{s}; T_i = 125^{\circ}\text{C}$	-	1.5	5.5	Α
I <sub>rrm</sub>	Peak reverse recovery current	$d_{I_F}/dt = 50 \text{ A/}\mu\text{s}, \ T_i = 125 \text{ C}$ $I_F = 8 \text{ A}; \ V_R = 400 \text{ V};$ $d_{I_F}/dt = 500 \text{ A/}\mu\text{s}; \ T_j = 125 ^{\circ}\text{C}$	-	9.5	12	Α
V <sub>fr</sub>	Forward recovery voltage	$I_F = 10 \text{ A}; dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	8	10	V

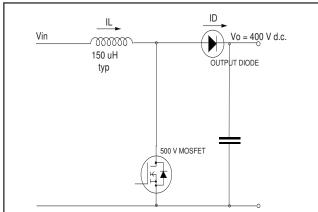


Fig.1. Typical application, output rectifier in boost converter power factor correction circuit. Continuous conduction, mode where the transistor turns on whilst forward current is still flowing in the diode.

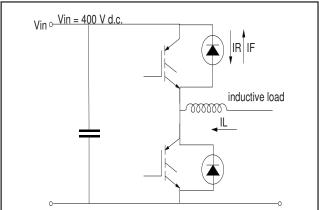


Fig.2. Typical application, freewheeling diode in half bridge converter. Continuous conduction mode, where each transistor turns on whilst forward current is still flowing in the other bridge leg diode.

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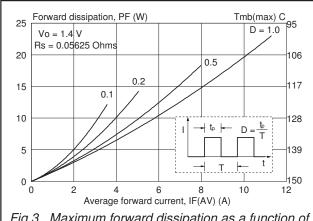


Fig.3. Maximum forward dissipation as a function of average forward current; rectangular current waveform where  $I_{F(AV)} = I_{F(RMS)} \times \sqrt{D}$ .

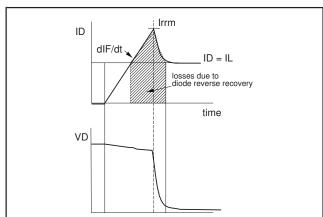


Fig.6. Origin of switching losses in transistor due to diode reverse recovery.

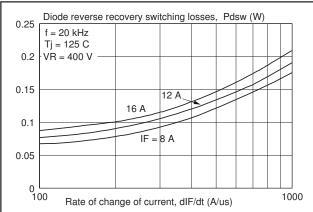


Fig.4. Typical reverse recovery switching losses in diode, as a function of rate of change of current dl<sub>F</sub>/dt.

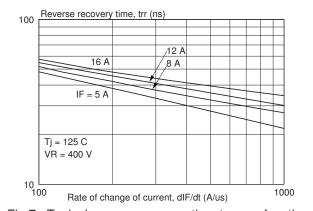


Fig.7. Typical reverse recovery time  $t_{rr}$ , as a function of rate of change of current  $dl_{r}/dt$ .

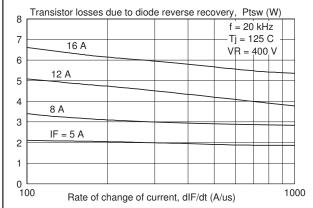


Fig.5. Typical switching losses in transistor due to reverse recovery of diode, as a function of of change of current dl<sub>p</sub>/dt.

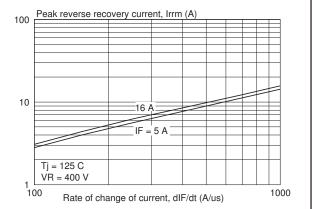
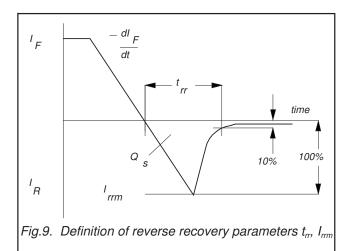


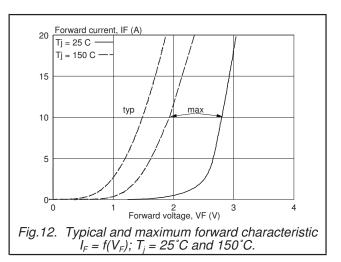
Fig.8. Typical peak reverse recovery current, I<sub>rrm</sub> as a function of rate of change of current dI<sub>r</sub>/dt.

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Peak forward recovery voltage, Vfr (V)

Tj = 25 C
IF = 10 A

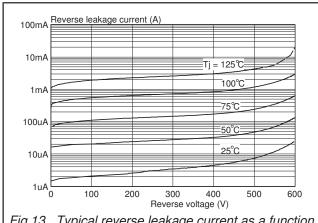
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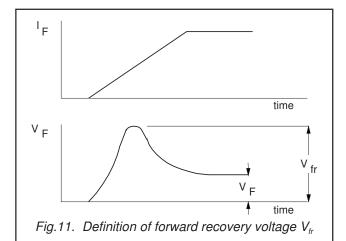
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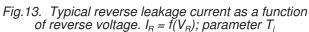
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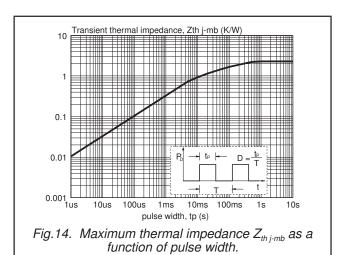
Rate of change of current, dIF/dt (A/ s)

Fig. 10. Typical forward recovery voltage, V<sub>fr</sub> as a function of rate of change of current dI<sub>F</sub>/dt.







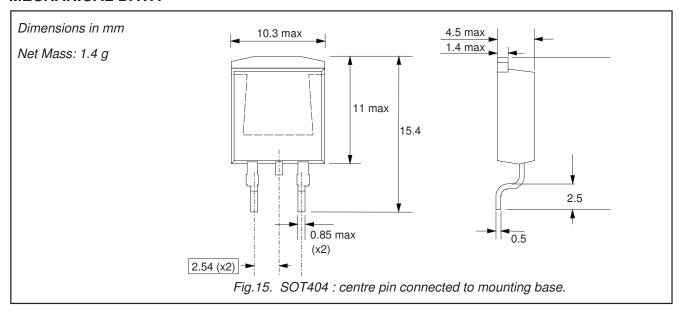


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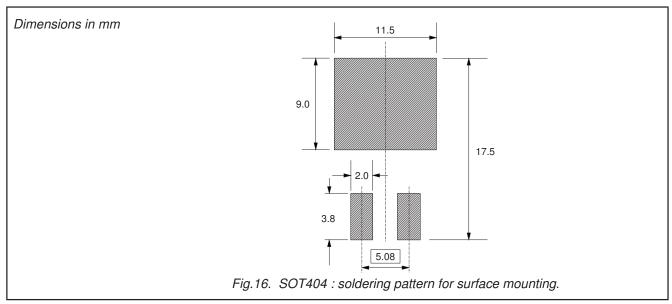
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#### **MECHANICAL DATA**



#### **MOUNTING INSTRUCTIONS**



#### **Notes**

1. Epoxy meets UL94 V0 at 1/8".

#### Legal information

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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